



## 产品规格书/Specification

产品/product:	介质浆料/ Dielectric paste
料号/part number:	09L-WE03

### 适用范围/Application:

This specification applies to thick film package paste.

该浆料适合于外层包封、芯片固定、粘结等。

### 使用条件/Operating conditions:

基材 Substrate	厚膜电路、玻璃、陶瓷、金属等 thick film circuit, glass, ceramic, metal, etc.
使用方法 Method of use	印刷, 200-250 目 Printing, 200-250mesh
流平 Levelling	5-10min minutes at room temperature 室温下流平 5-10 分钟 (时间根据流平的实际情况决定)。
固化 Curing conditions	通风烘箱烘烤 150~200℃, 20-30 分钟 (固化温度可以在 150-200℃范围内, 固化时间可根据实际情况决定) 150~200℃, 20-30 min ( It could be cured at a temperature between 150~ 200℃, but it depends of the thickness and the substrate.)
稀释剂 Thinner	ST-1001

### 性能/Characteristics:

#### 1. 浆料性能/Paste Characteristics:

性能 Characteristic	标准 Standard	测试方法及条件 Test method and conditions
1 细度 Fineness	≤8μm	FOG test
2 粘度 Viscosity	80~150Pa.s	Brookfield HBT utility cup and spindle (SC4-14/6R), 10rpm, 25±1℃, Brookfield HBT (博利飞) 粘度计, 转子 SC4-14/6R), 10rpm, 25±1℃
3 Appearance 外观	无色 Gray	



## 2. 烧结后特性/Characteristics after curing:

在 1 烧结条件下, Check fired film produced under the conditions specified in 1),

特性 Characteristics	Standard 标准	测试方法和条件 Test method and conditions
4 Acid resistance 耐酸性	Fine 良好	Marinate in 5% H2SO4, 30mins, no difference with standard sample 5%硫酸, 30 分钟无变化
5 Insulation resistance 绝缘系数	$\geq 10^4 M\Omega$	RCJ-30
6 Breakdown voltage 击穿电压	$\geq 300V$	CS262673A

### 保存条件, 有效期/Storage condition and Term of validity

产品应在 5-15°C 的环境温度下密封储存, 有效期为产品发货之日起 1 年。

The product shall be guaranteed for 1 year after shipping date, keep tightly under at 5-15°C

### 包装方式/Packaging method:

标准包装, 1000g/罐, 样品可提供 200 克小罐包装

Standard package 1000g/can, if you need sample to test, available 200g with small package.